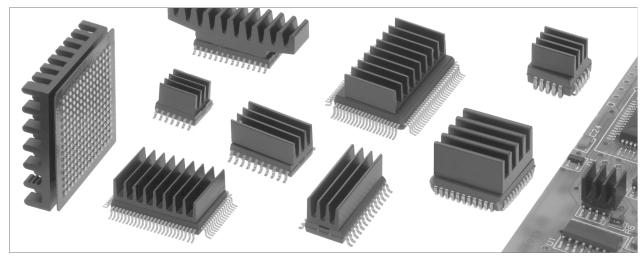
fischer elektronik 23

Heatsinks for DIL-IC, PLCC and SMD

B

G

Heatsinks for SMD



- particularly suitable for SMD components
- low profile
- reduced weight
- effective heat dissipation
- can be glued directly onto the component
- soudable versions
- customer specific versions on request
- special packaging like tape and real, bar magazin, tary etc. on request

₩ ₩ ₩ ₩ 1 - 6,3 - 1			
art. no.	R _{th} [K/W]	(→) [mm]	
ICK SMD A 5	123	5	
ICK SMD A 8	87	8	
ICK SMD A 10	75	10	
ICK SMD A 13	63	13	
ICK SMD A 17	51	17	
ICK SMD A 22	34	22	
		# 19 — † # 11111111	

art. no.	R _{th} [K/W]	(→) [mm]
ICK SMD B 5	56	5
ICK SMD B 7	47	7
ICK SMD B 10	35	10
ICK SMD B 13	29	13
ICK SMD B 19	22	19

please indicate:

... surface treatment **SA=black** anodised MI=solderable surface

B 25

Aluminium oxide wafers Mica wafers Kapton insulator washers **Insulting clamping parts**

E 9 - 10 E 11 E 8

Profiles for PCB components Heatsinks for PCB SMD-heatsinks Profiles for PCB mounting

→ A 89 A 87 B 25 - 27 → A 87 - 108